

Y506

2U Passive Heat Sink

PRODUCT SPECIFICATIONS

Model Number: Y506

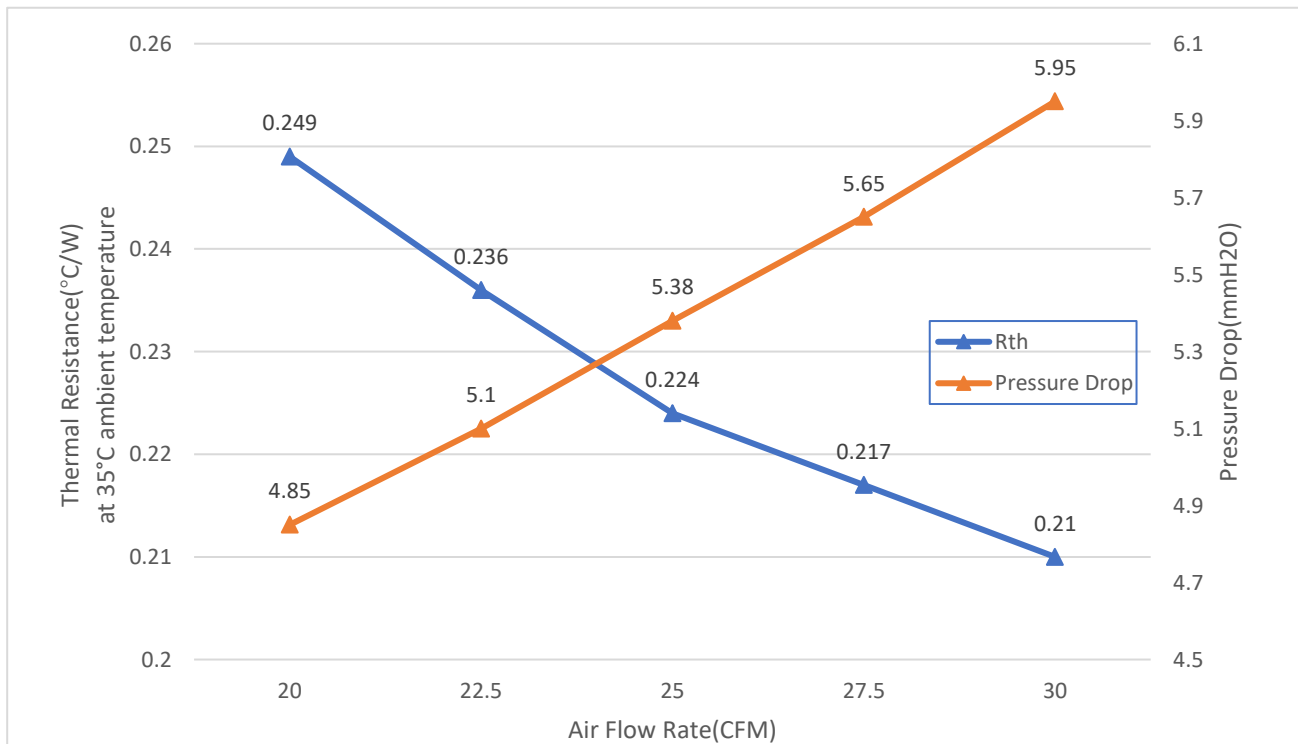
- Recommend for Intel® CPU as following
 - Intel® Xeon® Processor E3 v4 Family, Socket FCLGA 1150
 - Intel® Xeon® E Processor/Intel Core™ i7 Processor, Socket FCLGA 1151;
 - Intel® Xeon® Processor E3 Family/Intel Core™ i5 Processor, Socket LGA 1155;
 - Intel® Xeon® processor X3400, Socket LGA 1156;
 - Intel® Core™ i9 Processor, Socket FCLGA 1200;
- Passive Heat Sink for 2U Server

Overall Specification

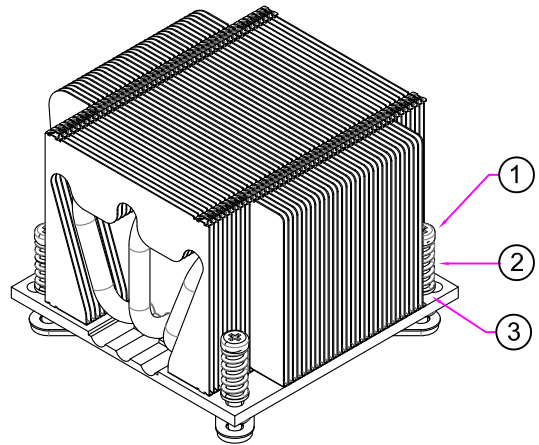
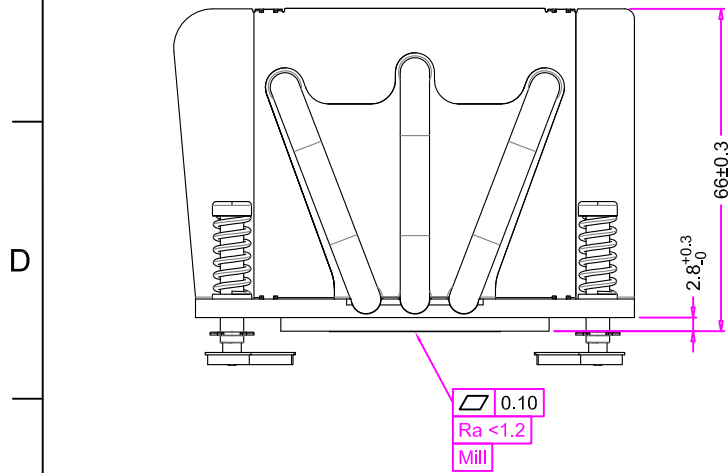
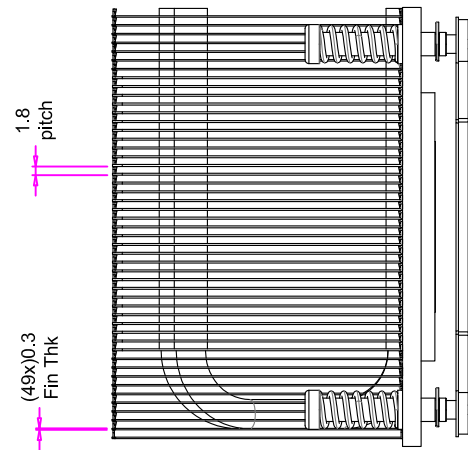
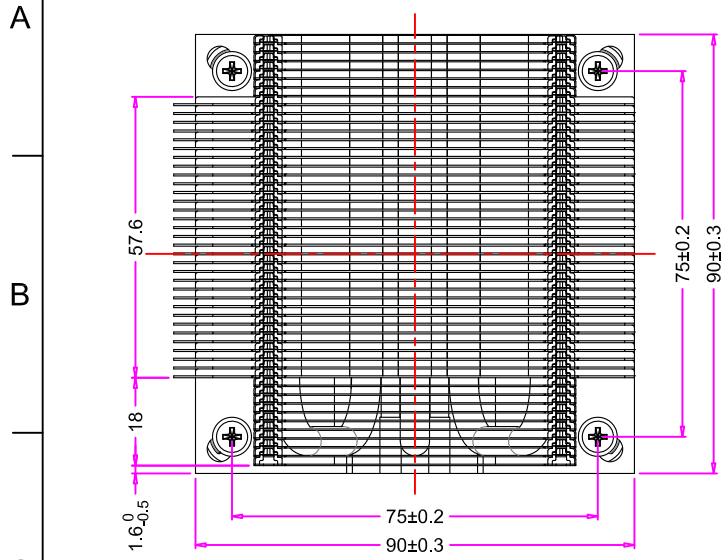
Dimension	90 x 90 x 66.0 mm
Weight	490 g
Material	Copper Base with Aluminum Stacked Fin plus 3 Heat Pipes
Back Strip	Included
Thermal Grease	Pre-Printed with SHIN-ETSU 7762 or Equivalent
TDP	Support 125 Watts CPU Power Heat Dissipation

Performance Chart: Y506 Thermal Resistance

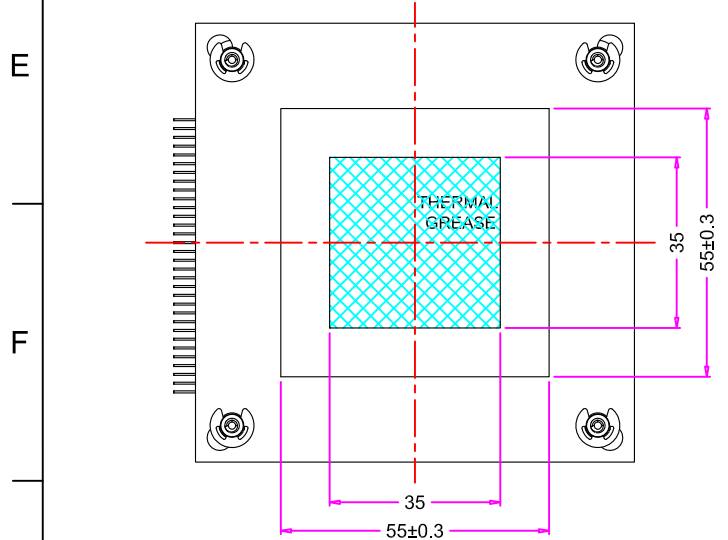
Thermal Performance vs. Airflow



REV#	DESCRIPTION	CHECKER	DATE
0.0	INITIAL RELEASE	LANG	06/02/2014



3D IMAGE IS NOT FOR SCALE



Bottom View with Back Strip Hidden

ITEM#	DESCRIPTION	MATERIAL	QTY.
7	BACK STRIP & INSULATOR	SPCC & PC	2
6	THERMAL GREASE	SHIN-ETSU 7762	1
5	C-RING	STEEL	4
4	HEATSINK	CU.BASE + Ø6.0 HEATPIPE ALUMINUM FIN	1
3	WASHER	STEEL	4
2	SPRING	SUS 304 (0390G)	4
1	SCREW, HEATSINK	STEEL (1150G)	4

	NAME	DATE
DRAWN BY	ENGR	06/02/2014
CHECKED BY	LANG	06/02/2014
ENG. APPROVED		
MFG. APPROVED	-	-



DYNATRON CORPORATION

TITLE: **Passive Heatsink Y506**
BOM & Overall Dimension Drawing

CONFIDENTIAL DOCUMENT

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VIEW	
UNITS	MM

DWG. No: **DYN-BD-Y506**

REV. **0.0**